

N-Channel MOSFET 30V 197A P-PAK5X6

MFT3N44P56

MERITEK

FEATURE

- Operating temperature: -55 ~ +150 °C
- Super high dense cell design for extremely low RDS(ON)
- High power and current handing capability
- Low Profile Compact Construction Design



MAXIMUM RATINGS

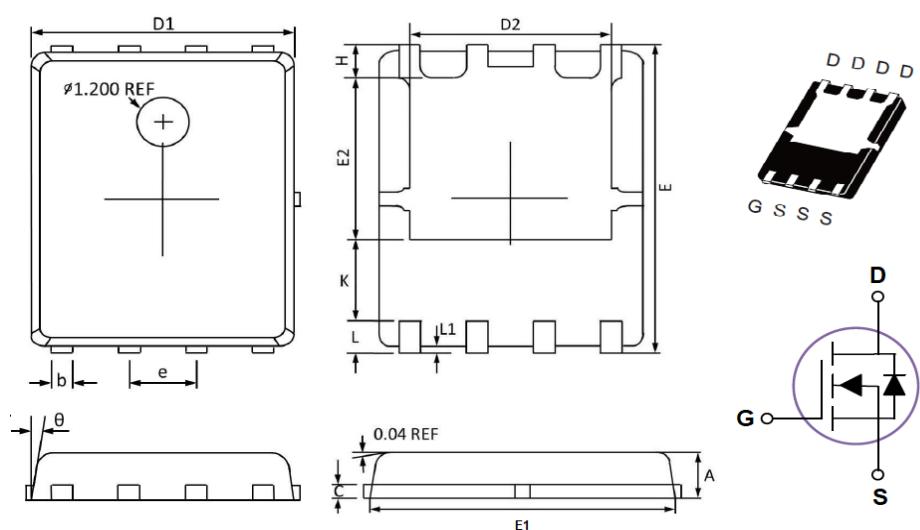
Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	30	V
Gate-Source Voltage	V _{GS}	±20	V
Drain Current – Continuous	at R _{θJA}	I _D	A
	at R _{θJC}	I _D	A
Drain Current – Pulsed	at R _{θJA}	I _{DM}	A
	at R _{θJC}	I _{DM}	A
Single Pulsed Avalanche Energy	E _{AS}	544	mJ
Single Pulsed Avalanche Current	I _{AS}	33	A
Power Dissipation	P _D	125	W
Operating Junction and Storage Temperature Range	T _{θJ/STG}	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance Junction to Ambient	R _{θJA}	20	°C/W
Thermal Resistance Junction to Case	R _{θJC}	1.0	°C/W

DIMENSIONS

Item	Min (mm)	Max (mm)
A	0.800	1.100
b	0.330	0.510
C	0.200	0.300
D1	4.800	5.100
D2	3.610	4.100
E	5.900	6.200
E1	5.700	5.900
E2	3.350	3.780
e	1.27BSC	
H	0.410	0.700
K	1.100	1.500
L	0.510	0.710
L1	0.060	0.200



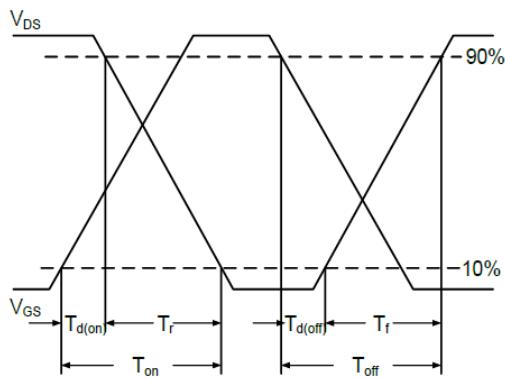
ELECTRICAL CHARACTERISTICS

Off Characteristics	Conditions	Symbol	Min	Typ.	Max	Unit
Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	BV_{DSS}	30	--	--	V
Drain-Source Leakage Current	$V_{DS}=60V, V_{GS}=0V$	I_{DSS}	--	--	1	μA
Gate Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	I_{GSS}	--	--	± 100	nA
On Characteristics	Conditions	Symbol	Min	Typ.	Max	Unit
Static Drain-Source On-Resistance	$V_{GS}=10V, I_D=30A$	$R_{DS(ON)}$	--	1.5	2.0	$m\Omega$
	$V_{GS}=4.5V, I_D=30A$		--	2.1	2.8	$m\Omega$
Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	$V_{GS(th)}$	1.0	--	3.0	V
Dynamic Characteristics	Conditions	Symbol	Min	Typ.	Max	Unit
Total Gate Charge	$V_{DS}=24V, V_{GS}=4.5V, I_D=50A$	Q_g	--	34	--	nC
Gate-Source Charge		Q_{gs}	--	11	--	
Gate-Drain Charge		Q_{gd}	--	15	--	
Turn-On Delay Time	$V_{DD}=24V, I_D=50A$ $V_{GS}=10V, R_{GEN}=6\Omega$	$T_{d(on)}$	--	44	--	nS
Rise Time		T_r	--	26	--	
Turn-Off Delay Time		$T_{d(off)}$	--	80	--	
Fall Time		T_f	--	16	--	
Input Capacitance	$V_{DS}=25V, V_{GS}=0V$ $F=1.0MHz$	C_{iss}	--	4240	--	pF
Output Capacitance		C_{oss}	--	820	--	
Reverse Transfer Capacitance		C_{rss}	--	145	--	
Gate resistance	$V_{GS}=0V, V_{DS}=0V, F=1MHz$	R_g	--	1.2	--	Ω
Drain-Sourse Body Diode	Conditions	Symbol	Min	Typ.	Max	Unit
Continuous Source Current	--	I_s	--	--	100	A
Drain-Source Diode Forward Voltage	$V_{GS}=0V, I_s=30A$	V_{SD}	--	--	1.2	V

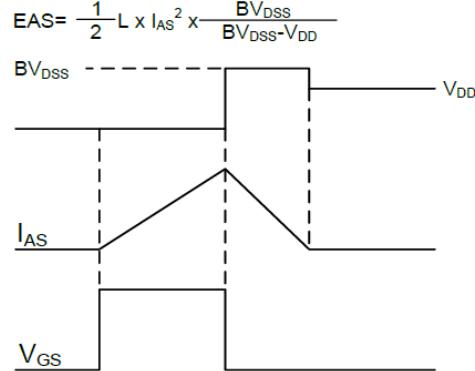
Note:

- Repetitive Rating : Pulsed width limited by maximum junction temperature.
- $V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=79A$, Starting $TJ=25^\circ C$
- The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
- Essentially independent of operating temperature

Switching Time Waveform



EAS Waveform

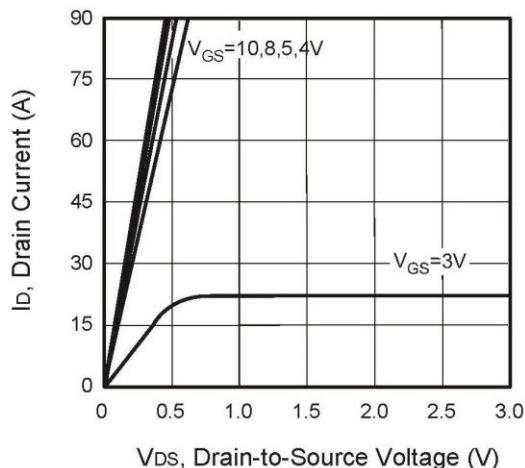


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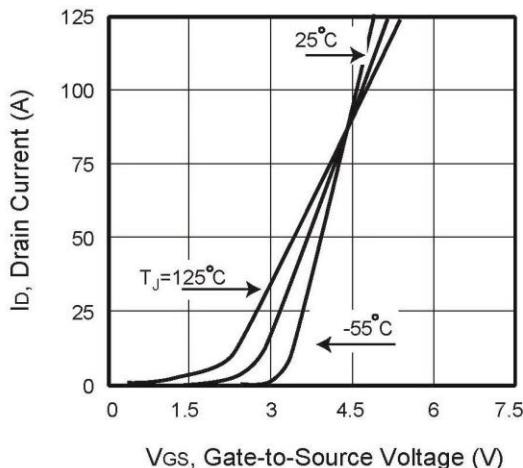
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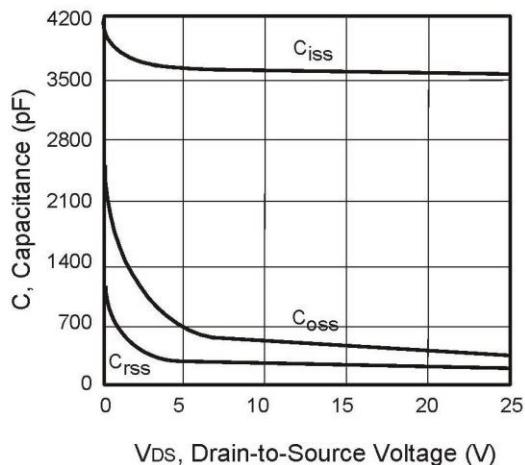
CHARACTERISTIC CURVES



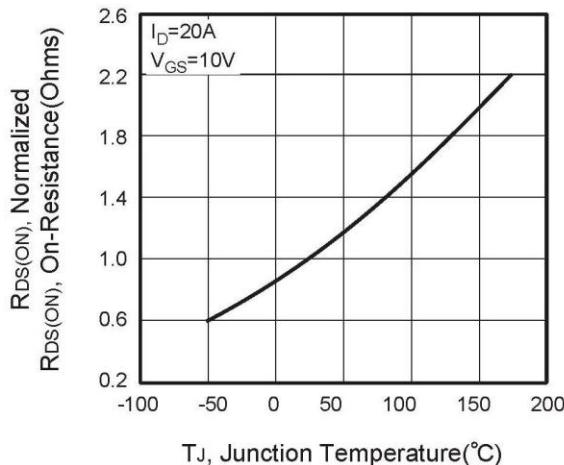
Output Characteristics



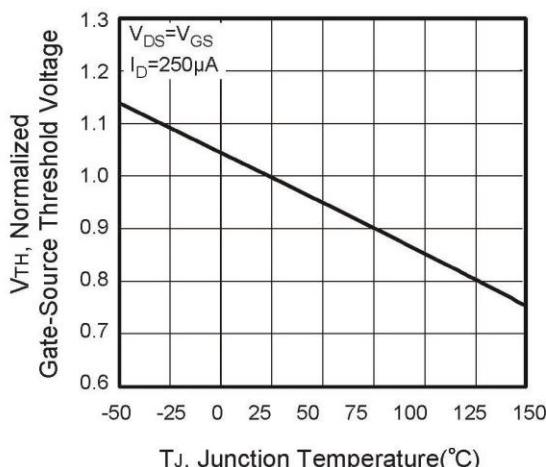
Transfer Characteristics



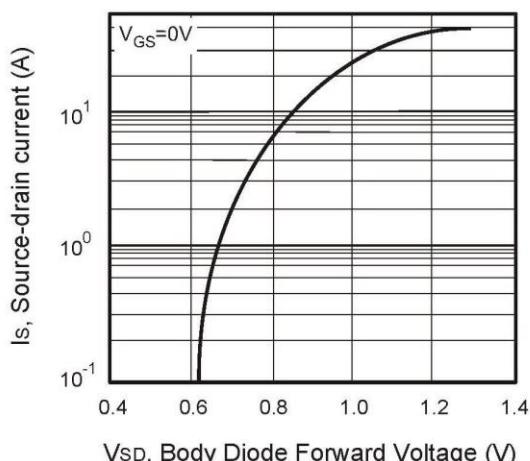
Capacitance



On-Resistance Variation with Temperature



Gate Threshold Variation with Temperature



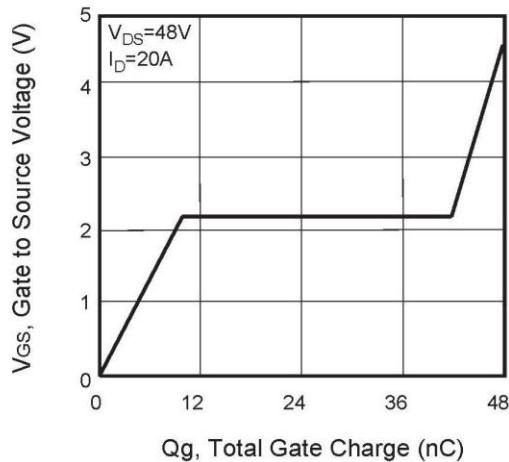
Body Diode Forward Voltage Variation with Source Current

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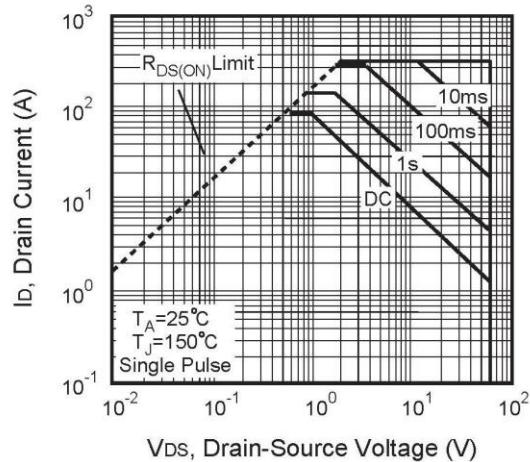
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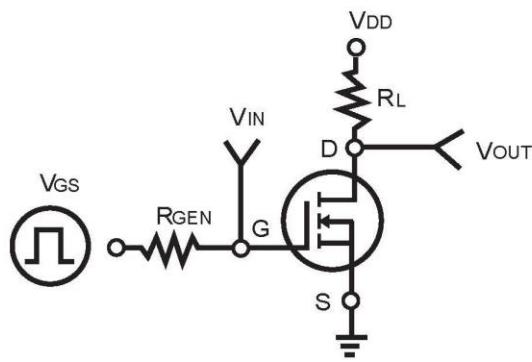
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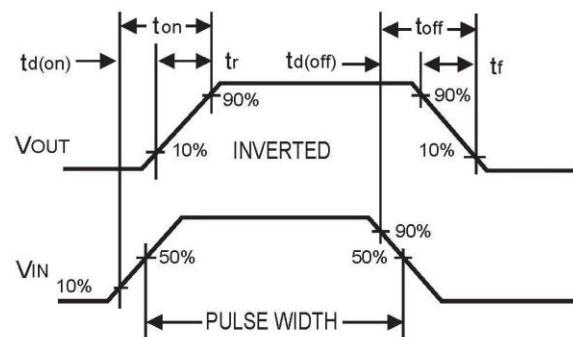
Gate Charge



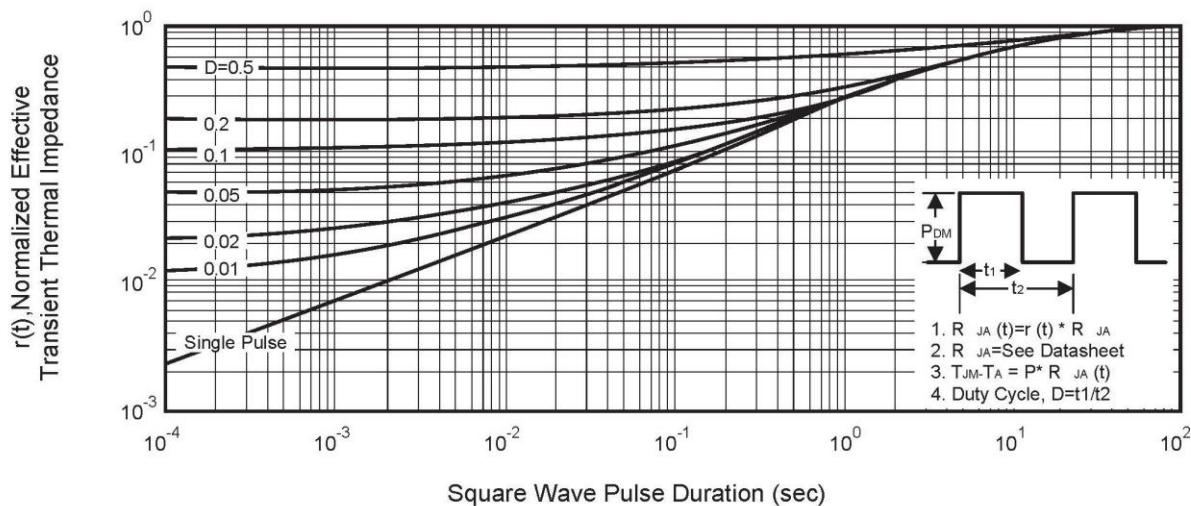
Maximum Safe
Operating Area



Switching Test Circuit



Switching Waveforms



Normalized Thermal Transient Impedance Curve

*Specifications subject to change without notice.